

L Number	Hits	Search Text	DB	Time stamp
49	2958	(chip or die or ic or integrated adj circuit) and (package or packaging or housing) and (lead or lead adj frame or leadframe) near2 (shape or shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:14
50	2765	(chip or die or ic or integrated adj circuit) and (package or packaging or housing) and (lead) near2 (shape or shaped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:14
51	13	(chip or die or ic or integrated adj circuit) and (package or packaging or housing) and (lead or leadframe or lead adj frame) near2 small adj footprint	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:16
52	875	257/696.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:18
53	54	257/696.ccls. and lead near3 (angled or angle or inclined or incline or angling or degrees or acute or obtuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:26
54	75	257/692.ccls. and lead near3 (angled or angle or inclined or incline or angling or degrees or acute or obtuse)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:27
-	0	package and die and diepad and lead and (foot or footprint) near4 (wetting or inclined or inclination or angled or angle or bent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:31
-	6545	(package or packaging) and (lead or foot or footprint) near4 (wetting or inclined or inclination or angled or angle or bent or folded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:32
-	6097	(package or packaging) and (lead or foot or footprint) near4 (wetting or inclined or inclination or angled or angle or bent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:32
-	2538	(package or packaging) and (lead or foot or footprint) near4 (wetting or inclined or inclination or angled or angle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:18
-	554	(package or packaging) and (lead or foot or footprint) near4 (wetting or inclined or inclination or angled or angle) and (lead or foot or footprint) near4 (beneath or under or underneath or below or back)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 15:39
-	326	(chip or die or ic) and (package or packaging) and (lead or foot or footprint) near4 (wetting or inclined or inclination or angled or angle) and (lead or foot or footprint) near4 (beneath or under or underneath or below or back)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:15
-	11	(package or packaging) and (lead or foot or footprint) near3 solder adj wetting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:40
-	914	(package or packaging or housing) and (lead or lead adj frame or leadframe or package) near3 (footprint or foot adj print)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:40

-	349	(package or packaging or housing) and (lead or lead adj frame or leadframe or package) near3 (footprint or foot adj print) near5 (reduced or small or little or smaller or decrease or reduce or decreased)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:53
-	1572	(package or packaging or housing) and (lead or lead adj frame or leadframe or package) near3 (footprint or foot adj print or area) near5 (reduced or small or little or smaller or decrease or reduce or decreased) not bga	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 16:53
-	191	(package or packaging or housing) and (lead or lead adj frame or leadframe or package) near3 (footprint or foot adj print) near5 (reduced or small or little or smaller or decrease or reduce or decreased) not bga	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 09:09